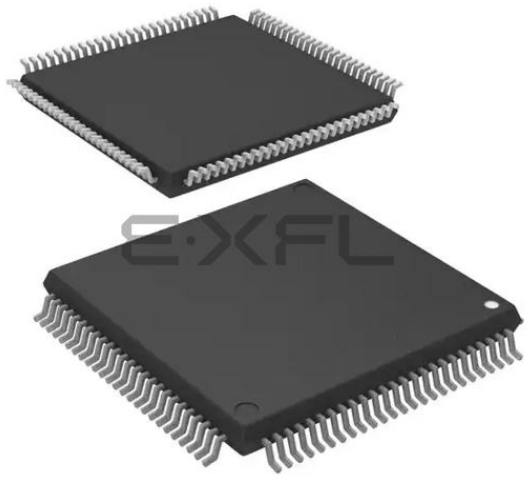
Renesas Electronics America Inc - M30302SPGP#U3 Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	M16C/60
Core Size	16-Bit
Speed	16MHz
Connectivity	I²C, IEBus, UART/USART
Peripherals	DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 18x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30302spgp-u3

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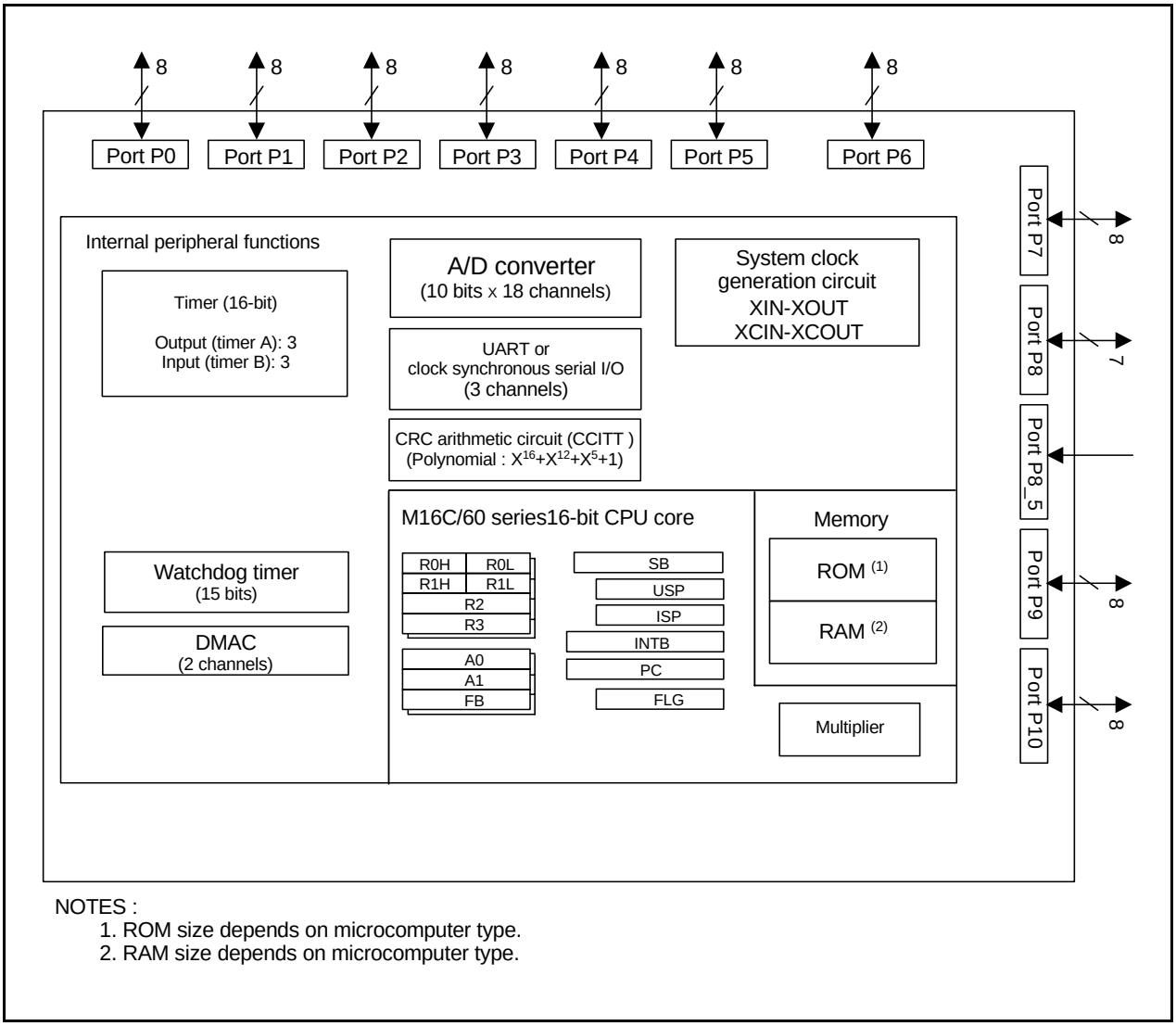
1.3 Block Diagram

Figure 1.1 is a M16C/30P Group Block Diagram.



NOTES :
1. ROM size depends on microcomputer type.
2. RAM size depends on microcomputer type.

Figure 1.1 M16C/30P Group Block Diagram

1.4 Product List

Table 1.2 lists the M16C/30P group products and Figure 1.2 shows the Part No., Memory Size, and Package. Table 1.4 lists Product Code of MASK ROM version for M16C/30P. Figure 1.3 shows the Marking Diagram of Mask ROM Version for M16C/30P (Top View). Table 1.5 lists Product Code of One Time Flash version, Flash Memory version, and ROM-less version for M16C/30P. Figure 1.4 shows the Marking Diagram of One Time Flash version, Flash Memory version, and ROM-less Version for M16C/30P (Top View). Please specify the marking for M16C30P (MASK ROM version) when placing an order for ROM.

Table 1.2 Product List (1) **As of March 2007**

Part No.	ROM Capacity	RAM Capacity	package code (1)	Remarks
M30302MAP-XXXFP	96 Kbytes	5 Kbytes	PRQP0100JB-A	Mask ROM version
M30302MAP-XXXGP			PLQP0100KB-A	
M30302MCP-XXXFP	128 Kbytes		PRQP0100JB-A	
M30302MCP-XXXGP			PLQP0100KB-A	
M30302MDP-XXXFP	160 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302MDP-XXXGP			PLQP0100KB-A	
M30302MEP-XXXFP	192 Kbytes		PRQP0100JB-A	
M30302MEP-XXXGP			PLQP0100KB-A	
M30302GAPFP	96 Kbytes	5 Kbytes	PRQP0100JB-A	One Time Flash version (blank product)
M30302GAPGP (D)			PLQP0100KB-A	
M30302GCPFP	128 Kbytes		PRQP0100JB-A	
M30302GCPGP (D)			PLQP0100KB-A	
M30302GDPFP	160 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302GDPGP (D)			PLQP0100KB-A	
M30304GDPFP (D)		12 Kbytes	PRQP0100JB-A	
M30304GDPGP (D)			PLQP0100KB-A	
M30302GEPFP	192 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302GEPGP (D)			PLQP0100KB-A	
M30304GEPFP (D)		12 Kbytes	PRQP0100JB-A	
M30304GEPGP (D)			PLQP0100KB-A	
M30302GGPFP (D)	256 Kbytes	12 Kbytes	PRQP0100JB-A	
M30302GGPGP (D)			PLQP0100KB-A	
M30302GAP-XXXFP	96 Kbytes	5 Kbytes	PRQP0100JB-A	One Time Flash version (factory programmed product)
M30302GAPvGP (D)			PLQP0100KB-A	
M30302GCP-XXXFP	128 Kbytes		PRQP0100JB-A	
M30302GCP-XXXGP (D)			PLQP0100KB-A	
M30302GDP-XXXFP	160 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302GDP-XXXGP (D)			PLQP0100KB-A	
M30304GDP-XXXFP (D)		12 Kbytes	PRQP0100JB-A	
M30304GDP-XXXGP (D)			PLQP0100KB-A	
M30302GEP-XXXFP	192 Kbytes	6 Kbytes	PRQP0100JB-A	
M30302GEP-XXXGP (D)			PLQP0100KB-A	
M30304GEP-XXXFP (D)		12 Kbytes	PRQP0100JB-A	
M30304GEP-XXXGP (D)			PLQP0100KB-A	
M30302GGP-XXXFP (D)	256 Kbytes	12 Kbytes	PRQP0100JB-A	
M30302GGP-XXXGP (D)			PLQP0100KB-A	

(D): Under development
(P): Under planning
NOTES:
1. Previous package codes are as follows.
   PRQP0100JB-A : 100P6S-A,
   PLQP0100KB-A : 100P6Q-A
2. Block A (4-Kbytes space) is available in flash memory version.

Table 1.7 Pin Characteristics (2)

Pin No.		Control Pin	Port	Interrupt Pin	Timer Pin	UART Pin	Analog Pin	Bus Control Pin
FP	GP							
51	49		P4_3					A19
52	50		P4_2					A18
53	51		P4_1					A17
54	52		P4_0					A16
55	53		P3_7					A15
56	54		P3_6					A14
57	55		P3_5					A13
58	56		P3_4					A12
59	57		P3_3					A11
60	58		P3_2					A10
61	59		P3_1					A9
62	60	VCC2						
63	61		P3_0					A8
64	62	VSS						
65	63		P2_7					A7
66	64		P2_6					A6
67	65		P2_5					A5
68	66		P2_4					A4
69	67		P2_3					A3
70	68		P2_2					A2
71	69		P2_1					A1
72	70		P2_0					A0
73	71		P1_7					D15
74	72		P1_6	$\overline{\text{INT4}}$				D14
75	73		P1_5	$\overline{\text{INT3}}$				D13
76	74		P1_4					D12
77	75		P1_3					D11
78	76		P1_2					D10
79	77		P1_1					D9
80	78		P1_0					D8
81	79		P0_7				AN0_7	D7
82	80		P0_6				AN0_6	D6
83	81		P0_5				AN0_5	D5
84	82		P0_4				AN0_4	D4
85	83		P0_3				AN0_3	D3
86	84		P0_2				AN0_2	D2
87	85		P0_1				AN0_1	D1
88	86		P0_0				AN0_0	D0
89	87		P10_7	$\overline{\text{KI3}}$			AN7	
90	88		P10_6	$\overline{\text{KI2}}$			AN6	
91	89		P10_5	$\overline{\text{KI1}}$			AN5	
92	90		P10_4	$\overline{\text{KI0}}$			AN4	
93	91		P10_3				AN3	
94	92		P10_2				AN2	
95	93		P10_1				AN1	
96	94	AVSS						
97	95		P10_0				AN0	
98	96	VREF						
99	97	AVCC						
100	98		P9_7				$\overline{\text{ADTRG}}$	

Table 4.2 SFR Information (2) (1)

Address	Register	Symbol	After Reset
0040h			
0041h			
0042h			
0043h			
0044h	INT3 Interrupt Control Register	INT3IC	XX00X000b
0045h			
0046h	UART1 BUS Collision Detection Interrupt Control Register	U1BCNIC	XXXXX000b
0047h	UART0 BUS Collision Detection Interrupt Control Register	U0BCNIC	XXXXX000b
0048h			
0049h	INT4 Interrupt Control Register	INT4IC	XX00X000b
004Ah	UART2 Bus Collision Detection Interrupt Control Register	BCNIC	XXXXX000b
004Bh	DMA0 Interrupt Control Register	DM0IC	XXXXX000b
004Ch	DMA1 Interrupt Control Register	DM1IC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
0050h	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	Timer A0 Interrupt Control Register	TA0IC	XXXXX000b
0056h	Timer A1 Interrupt Control Register	TA1IC	XXXXX000b
0057h	Timer A2 Interrupt Control Register	TA2IC	XXXXX000b
0058h			
0059h			
005Ah	Timer B0 Interrupt Control Register	TB0IC	XXXXX000b
005Bh	Timer B1 Interrupt Control Register	TB1IC	XXXXX000b
005Ch	Timer B2 Interrupt Control Register	TB2IC	XXXXX000b
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Fh	INT2 Interrupt Control Register	INT2IC	XX00X000b
0060h to 01AFh			
01B0h			
01B1h			
01B2h			
01B3h			
01B4h			
01B5h	Flash Memory Control Register 1 (2)	FMR1	0X00XX0Xb
01B6h			
01B7h	Flash Memory Control Register 0 (3)	FMR0	00000001b
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			
01C0h to 024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh	Peripheral Clock Select Register	PCLKR	00000011b
025Fh			
0260h to 033Fh			

NOTES:
1. The blank areas are reserved and cannot be accessed by users.
2. This register is included in the flash memory version.
3. This register is included in the flash memory version and one time flash version.

X : Nothing is mapped to this bit

Table 4.4 SFR Information (4) (1)

Address	Register	Symbol	After Reset
0380h	Count Start Flag	TABSR	000XX000b
0381h	Clock Prescaler Reset Fag	CPSRF	0XXXXXXXb
0382h	One-Shot Start Flag	ONSF	00XXX000b
0383h	Trigger Select Register	TRGSR	XXXX0000b
0384h	Up-Down Flag	UDF	XX0XX000b (2)
0385h			
0386h 0387h	Timer A0 Register	TA0	XXh XXh
0388h 0389h	Timer A1 Register	TA1	XXh XXh
038Ah 038Bh	Timer A2 Register	TA2	XXh XXh
038Ch			
038Dh			
038Eh			
038Fh			
0390h 0391h	Timer B0 Register	TB0	XXh XXh
0392h 0393h	Timer B1 Register	TB1	XXh XXh
0394h 0395h	Timer B2 Register	TB2	XXh XXh
0396h	Timer A0 Mode Register	TA0MR	00h
0397h	Timer A1 Mode Register	TA1MR	00h
0398h	Timer A2 Mode Register	TA2MR	00h
0399h			
039Ah			
039Bh	Timer B0 Mode Register	TB0MR	00XX0000b
039Ch	Timer B1 Mode Register	TB1MR	00XX0000b
039Dh	Timer B2 Mode Register	TB2MR	00XX0000b
039Eh			
039Fh			
03A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
03A1h	UART0 Bit Rate Generator	U0BRG	XXh
03A2h 03A3h	UART0 Transmit Buffer Register	U0TB	XXh XXh
03A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
03A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
03A6h 03A7h	UART0 Receive Buffer Register	U0RB	XXh XXh
03A8h	UART1 Transmit/Receive Mode Register	U1MR	00h
03A9h	UART1 Bit Rate Generator	U1BRG	XXh
03AAh 03ABh	UART1 Transmit Buffer Register	U1TB	XXh XXh
03ACh	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
03ADh	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
03AEh 03AFh	UART1 Receive Buffer Register	U1RB	XXh XXh
03B0h	UART Transmit/Receive Control Register 2	UCON	X0000000b
03B1h			
03B2h			
03B3h			
03B4h			
03B5h			
03B6h			
03B7h			
03B8h	DMA0 Request Factor Select Register	DM0SL	00h
03B9h			
03BAh	DMA1 Request Factor Select Register	DM1SL	00h
03BBh			
03BCh 03BDh	CRC Data Register	CRCD	XXh XXh
03BEh	CRC Input Register	CRCIN	XXh
03BFh			

NOTES:
1. The blank areas are reserved and cannot be accessed by users.
2. Bit 5 in the Up-down flag is “0” by reset. However, The values in these bits when read are indeterminate.

X : Nothing is mapped to this bit

Table 4.5 SFR Information (5) (1)

Address	Register	Symbol	After Reset
03C0h	A/D Register 0	AD0	XXh
03C1h			XXh
03C2h	A/D Register 1	AD1	XXh
03C3h			XXh
03C4h	A/D Register 2	AD2	XXh
03C5h			XXh
03C6h	A/D Register 3	AD3	XXh
03C7h			XXh
03C8h	A/D Register 4	AD4	XXh
03C9h			XXh
03CAh	A/D Register 5	AD5	XXh
03CBh			XXh
03CCh	A/D Register 6	AD6	XXh
03CDh			XXh
03CEh	A/D Register 7	AD7	XXh
03CFh			XXh
03D0h			
03D1h			
03D2h			
03D3h			
03D4h	A/D Control Register 2	ADCON2	XXX000X0b
03D5h			
03D6h	A/D Control Register 0	ADCON0	000X0XXXb
03D7h	A/D Control Register 1	ADCON1	00000XXXb
03D8h			
03D9h			
03DAh			
03DBh			
03DCh			
03DDh			
03DEh			
03DFh			
03E0h	Port P0 Register	P0	XXh
03E1h	Port P1 Register	P1	XXh
03E2h	Port P0 Direction Register	PD0	00h
03E3h	Port P1 Direction Register	PD1	00h
03E4h	Port P2 Register	P2	XXh
03E5h	Port P3 Register	P3	XXh
03E6h	Port P2 Direction Register	PD2	00h
03E7h	Port P3 Direction Register	PD3	00h
03E8h	Port P4 Register	P4	XXh
03E9h	Port P5 Register	P5	XXh
03EAh	Port P4 Direction Register	PD4	00h
03EBh	Port P5 Direction Register	PD5	00h
03ECh	Port P6 Register	P6	XXh
03EDh	Port P7 Register	P7	XXh
03EEh	Port P6 Direction Register	PD6	00h
03EFh	Port P7 Direction Register	PD7	00h
03F0h	Port P8 Register	P8	XXh
03F1h	Port P9 Register	P9	XXh
03F2h	Port P8 Direction Register	PD8	00X00000b
03F3h	Port P9 Direction Register	PD9	00h
03F4h	Port P10 Register	P10	XXh
03F5h			
03F6h	Port P10 Direction Register	PD10	00h
03F7h			
03F8h			
03F9h			
03FAh			
03FBh			
03FCh	Pull-Up Control Register 0	PUR0	00h
03FDh	Pull-Up Control Register 1	PUR1	00000000b (2) 00000010b (2)
03FEh	Pull-Up Control Register 2	PUR2	00h
03FFh	Port Control Register	PCR	00h

NOTES:
1. The blank areas are reserved and cannot be accessed by users.
2. At hardware reset, the register is as follows:
   - "00000000b" where "L" is inputted to the CNVSS pin
   - "00000010b" where "H" is inputted to the CNVSS pin

   At software reset, the register is as follows:
   - "00000000b" where the PM01 to PM00 bits in the PM0 register are "00b" (single-chip mode).
   - "00000010b" where the PM01 to PM00 bits in the PM0 register are "01b" (memory expansion mode) or "11b" (microprocessor mode).

X : Nothing is mapped to this bit

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V_{CC}	Supply Voltage(V_{CC1}=V_{CC2})		V_{CC1}=V_{CC2}=AVcc	–0.3 to 6.5	V
AVcc	Analog Supply Voltage		V_{CC1}=V_{CC2}=AVcc	–0.3 to 6.5	V
V_I	Input Voltage	$\overline{\text{RESET}}$, CNVSS, BYTE, P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, VREF, XIN		–0.3 to V_{CC}+0.3	V
		P7_0, P7_1		–0.3 to 6.5	V
V_O	Output Voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, XOUT		–0.3 to V_{CC}+0.3	V
		P7_0, P7_1		–0.3 to 6.5	V
P_d	Power Dissipation		–40°C<T_{opr}≤85°C	300	mW
T_{opr}	Operating Ambient Temperature	When the Microcomputer is Operating		–20 to 85 / –40 to 85	°C
		One Time Flash Program Erase		0 to 60	
		Flash Program Erase		0 to 60	
T_{stg}	Storage Temperature			–65 to 150	°C

Table 5.2 Recommended Operating Conditions (1)

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
V_{CC}	Supply Voltage (V_{CC1}=V_{CC2})		2.7	5.0	5.5	V
AVcc	Analog Supply Voltage			Vcc		V
Vss	Supply Voltage			0		V
AVss	Analog Supply Voltage			0		V
V_{IH}	HIGH Input Voltage	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7	0.8Vcc		Vcc	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (during single-chip mode)	0.8Vcc		Vcc	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (data input during memory expansion and microprocessor mode)	0.5Vcc		Vcc	V
		P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	0.8Vcc		Vcc	V
		P7_0, P7_1	0.8Vcc		6.5	V
V_{IL}	LOW Input Voltage	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7	0		0.2Vcc	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (during single-chip mode)	0		0.2Vcc	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (data input during memory expansion and microprocessor mode)	0		0.16Vcc	V
		P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	0		0.2Vcc	V
$I_{OH(peak)}$	HIGH Peak Output Current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7			−10.0	mA
$I_{OH(avg)}$	HIGH Average Output Current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7			−5.0	mA
$I_{OL(peak)}$	LOW Peak Output Current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7			10.0	mA
$I_{OL(avg)}$	LOW Average Output Current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7			5.0	mA
f(XIN)	Main Clock Input Oscillation Frequency (4)	Vcc=3.0V to 5.5V	0		16	MHz
		Vcc=2.7V to 3.0V	0		20×V_{CC1}−44	MHz
f(XCIN)	Sub-Clock Oscillation Frequency			32.768	50	kHz
f(BCLK)	CPU Operation Clock		0		16	MHz

NOTES:
1. Referenced to V_{CC1} = V_{CC2} = 2.7 to 5.5V at T_{opr} = −20 to 85°C / −40 to 85°C unless otherwise specified.
2. The Average Output Current is the mean value within 100ms.
3. The total $I_{OL(peak)}$ for ports P0, P1, P2, P8_6, P8_7, P9 and P10 must be 80mA max. The total $I_{OL(peak)}$ for ports P3, P4, P5, P6, P7 and P8_0 to P8_4 must be 80mA max. The total $I_{OH(peak)}$ for ports P0, P1, and P2 must be −40mA max. The total $I_{OH(peak)}$ for ports P3, P4 and P5 must be −40mA max. The total $I_{OH(peak)}$ for ports P6, P7, and P8_0 to P8_4 must be −40mA max.
   The total $I_{OH(peak)}$ for ports P8_6, P8_7 and P9 must be −40mA max. Set Average Output Current to 1/2 of peak.
4. Relationship between main clock oscillation frequency, and supply voltage.

Main clock input oscillation frequency

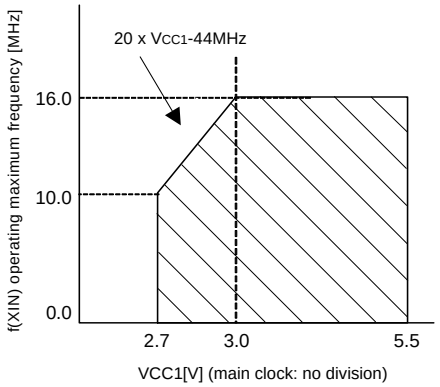


Table 5.4 Flash Memory Version Electrical Characteristics (1)

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
–	Program and Erase Endurance (2)		100(3)			cycle
–	Word Program Time (V_{CC1}=5.0V)			25	200	µs
–	Lock Bit Program Time			25	200	µs
–	Block Erase Time (V_{CC1}=5.0V)	4-Kbyte block		0.3	4	s
–		8-Kbyte block		0.3	4	s
–		32-Kbyte block		0.5	4	s
–		64-Kbyte block		0.8	4	s
t_{PS}	Flash Memory Circuit Stabilization Wait Time				15	µs
–	Data Hold Time (4)		10			year

NOTES:
1. Referenced to V_{CC1}=4.5 to 5.5V, 3.0 to 3.6V at Topr = 0 to 60 °C (U3, U5) unless otherwise specified.
2. Program and Erase Endurance refers to the number of times a block erase can be performed.
   If the program and erase endurance is 100, each block can be erased 100 times.
   For example, if a 4 Kbytes block A is erased after writing 1 word data 2,048 times, each to a different address, this counts as one program and erase endurance. Data cannot be written to the same address more than once without erasing the block. (Rewrite prohibited)
3. Maximum number of E/W cycles for which operation is guaranteed.
4. Topr = -40 to 85 °C (U3) / -20 to 85 °C (U5).

Table 5.5 Flash Memory Version Program / Erase Voltage and Read Operation Voltage Characteristics

Flash Program, Erase Voltage	Flash Read Operation Voltage
V_{CC1} = 3.3 ± 0.3 V or 5.0 ± 0.5 (T_{opr} = 0°C to 60°C)	V_{CC1}=2.7 to 5.5 V (T_{opr} = -40°C to 85°C (U3) -20°C to 85°C (U5))

$V_{CC1}=V_{CC2}=5V$

Table 5.9 Electrical Characteristics(1) (1)

Symbol	Parameter		Measuring Condition	Standard			Unit
				Min.	Typ.	Max.	
V_{OH}	HIGH Output Voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7	I_{OH}=–5mA	V_{CC}–2.0		V_{CC}	V
V_{OH}	HIGH Output Voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7	I_{OH}=–200µA	V_{CC}–0.3		V_{CC}	V
V_{OH}	HIGH Output Voltage XOUT	HIGHPOWER	I_{OH}=–1mA	V_{CC}–2.0		V_{CC}	V
		LOWPOWER	I_{OH}=–0.5mA	V_{CC}–2.0		V_{CC}	
	HIGH Output Voltage XCOUT	HIGHPOWER	With no load applied		2.5		V
		LOWPOWER	With no load applied		1.6		
V_{OL}	LOW Output Voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7	I_{OL}=5mA			2.0	V
V_{OL}	LOW Output Voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7	I_{OL}=200µA			0.45	V
V_{OL}	LOW Output Voltage XOUT	HIGHPOWER	I_{OL}=1mA			2.0	V
		LOWPOWER	I_{OL}=0.5mA			2.0	
	LOW Output Voltage XCOUT	HIGHPOWER	With no load applied		0		V
		LOWPOWER	With no load applied		0		
V_{T+}-V_{T-}	Hysteresis	TA0IN to TA2IN, TB0IN to TB2IN, $\overline{INT0}$ to $\overline{INT4}$, $\overline{NMI}$, $\overline{ADTRG}$, $\overline{CTS0}$ to $\overline{CTS2}$, CLK0 to CLK2, TA0OUT to TA2OUT, $\overline{KI0}$ to $\overline{KI3}$, RXD0 to RXD2, SCL0 to SCL2, SDA0 to SDA2		0.2		1.0	V
V_{T+}-V_{T-}	Hysteresis	$\overline{RESET}$		0.2		2.5	V
I_{IH}	HIGH Input Current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, XIN, $\overline{RESET}$, CNVSS, BYTE	V_I=5V			5.0	µA
I_{IL}	LOW Input Current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, XIN, $\overline{RESET}$, CNVSS, BYTE	V_I=0V			–5.0	µA
R_{PULLUP}	Pull-Up Resistance	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7	V_I=0V	30	50	170	kΩ
R_{fXIN}	Feedback Resistance XIN				1.5		MΩ
R_{fXCIN}	Feedback Resistance XCIN				15		MΩ
V_{RAM}	RAM Retention Voltage		At stop mode	2.0			V

NOTES:
1. Referenced to $V_{CC1}=V_{CC2}$=4.2 to 5.5V, V_{SS} = 0V at T_{opr} = –20 to 85°C / –40 to 85°C, f(XIN) =16MHz unless otherwise specified.

Table 5.10 Electrical Characteristics (2) (1)

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
I_{CC}	Power Supply Current (V_{CC1}=V_{CC2}=4.0V to 5.5V)	In single-chip mode, the output pins are open and other pins are V_{SS}	Mask ROM	f(XIN)=16MHz No division		10	15	mA
			One Time Flash	f(XIN)=16MHz, No division		10	18	mA
			Flash Memory	f(XIN)=16MHz, No division		12	18	mA
			One Time Flash	f(XIN)=10MHz, VCC1=5.0V		15		mA
			Flash Memory Program	f(XIN)=10MHz, VCC1=5.0V		15		mA
			Flash Memory Erase	f(XIN)=10MHz, VCC1=5.0V		25		mA
			Mask ROM	f(XCIN)=32kHz Low power dissipation mode, ROM (3)		25		µA
			One Time Flash	f(XCIN)=32kHz Low power dissipation mode, RAM (3)		25		µA
				f(XCIN)=32kHz Low power dissipation mode, Flash Memory (3)		350		µA
			Flash Memory	f(XCIN)=32kHz Low power dissipation mode, RAM (3)		25		µA
				f(XCIN)=32kHz Low power dissipation mode, Flash Memory (3)		420		µA
			Mask ROM One Time Flash Flash Memory	f(XCIN)=32kHz Wait mode (2), Oscillation capability High		7.5		µA
				f(XCIN)=32kHz Wait mode (2), Oscillation capability Low		2.0		µA
				Stop mode Topr =25°C		0.8	3.0	µA

NOTES:
1. Referenced to V_{CC1}=V_{CC2}=4.2 to 5.5V, V_{SS} = 0V at T_{opr} = –20 to 85°C / –40 to 85°C, f(XIN)=16MHz unless otherwise specified.
2. With one timer operated using fC32.
3. This indicates the memory in which the program to be executed exists.

$V_{CC1}=V_{CC2}=5V$

Timing Requirements

(V_{CC1} = V_{CC2} = 5V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.11 External Clock Input (XIN input) (1)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External Clock Input Cycle Time	62.5		ns
$t_{w(H)}$	External Clock Input HIGH Pulse Width	25		ns
$t_{w(L)}$	External Clock Input LOW Pulse Width	25		ns
t_r	External Clock Rise Time		15	ns
t_f	External Clock Fall Time		15	ns

NOTES:
1. The condition is V_{CC1}=V_{CC2}=3.0 to 5.0V.

Table 5.12 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data Input Access Time (for setting with no wait)		(NOTE 1)	ns
$t_{ac2(RD-DB)}$	Data Input Access Time (for setting with wait)		(NOTE 2)	ns
$t_{su(DB-RD)}$	Data Input Setup Time	40		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ Input Setup Time	30		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ Input Setup Time	40		ns
$t_{h(RD-DB)}$	Data Input Hold Time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ Input Hold Time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ Input Hold Time	0		ns

NOTES:
1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 45[ns]$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 45[ns]$$ n is "2" for 1-wait setting.

$V_{CC1}=V_{CC2}=5V$

Switching Characteristics
(V_{CC1} = V_{CC2} = 5V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.26 Memory Expansion and Microprocessor Modes (for 1 wait setting and external area access)

Symbol	Parameter		Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address Output Delay Time	See **Figure 5.2**		25	ns
$t_{h(BCLK-AD)}$	Address Output Hold Time (in relation to BCLK)		–3		ns
$t_{h(RD-AD)}$	Address Output Hold Time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address Output Hold Time (in relation to WR)		(NOTE 2)		ns
$t_{d(BCLK-CS)}$	Chip Select Output Delay Time			25	ns
$t_{h(BCLK-CS)}$	Chip Select Output Hold Time (in relation to BCLK)		–3		ns
$t_{d(BCLK-ALE)}$	ALE Signal Output Delay Time			15	ns
$t_{h(BCLK-ALE)}$	ALE Signal Output Hold Time		–4		ns
$t_{d(BCLK-RD)}$	RD Signal Output Delay Time			25	ns
$t_{h(BCLK-RD)}$	RD Signal Output Hold Time		0		ns
$t_{d(BCLK-WR)}$	WR Signal Output Delay Time			25	ns
$t_{h(BCLK-WR)}$	WR Signal Output Hold Time		0		ns
$t_{d(BCLK-DB)}$	Data Output Delay Time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data Output Hold Time (in relation to BCLK) (3)		4		ns
$t_{d(DB-WR)}$	Data Output Delay Time (in relation to WR)		(NOTE 1)		ns
$t_{h(WR-DB)}$	Data Output Hold Time (in relation to WR)(3)		(NOTE 2)		ns
$t_{d(BCLK-HLDA)}$	HLDA Output Delay Time			40	ns

NOTES:

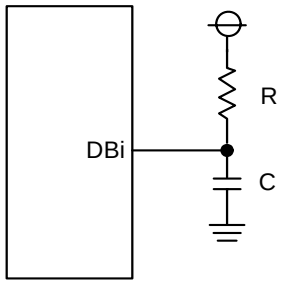
1. Calculated according to the BCLK frequency as follows:

$$\frac{(n-0.5)\times 10^9}{f(BCLK)} - 40[ns]$$ n is “1” for 1-wait setting, f(BCLK) is 12.5MHz or less.

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5\times 10^9}{f(BCLK)} - 10[ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
Hold time of data bus is expressed in
t = –CR X ln (1–V_{OL} / V_{CC1})
by a circuit of the right figure.
For example, when V_{OL} = 0.2V_{CC1}, C = 30pF, R = 1kΩ, hold time of output ”L” level is
t = –30pF X 1kΩ X ln(1–0.2V_{CC1} / V_{CC1})
= 6.7ns.



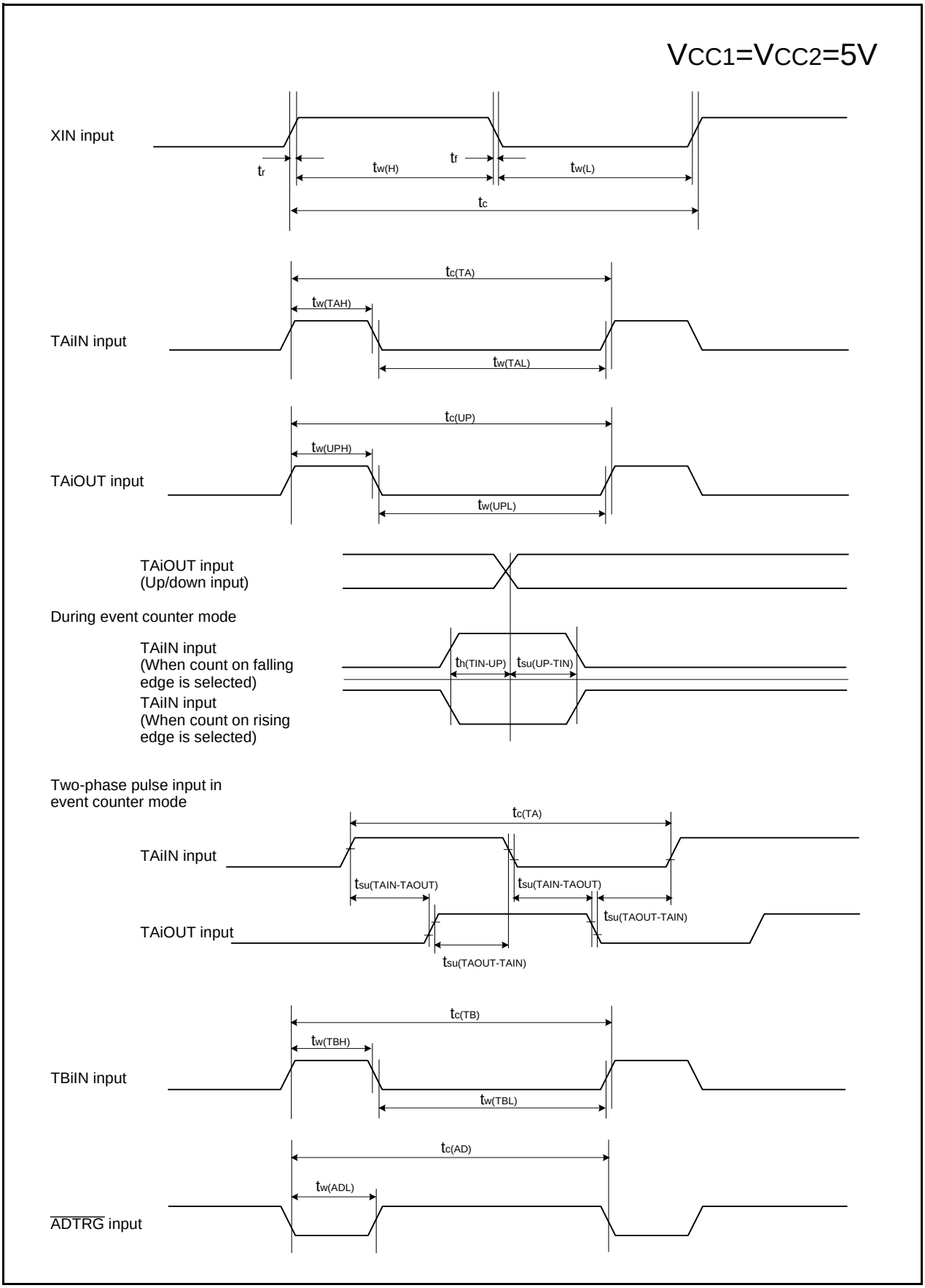


Figure 5.3 Timing Diagram (1)

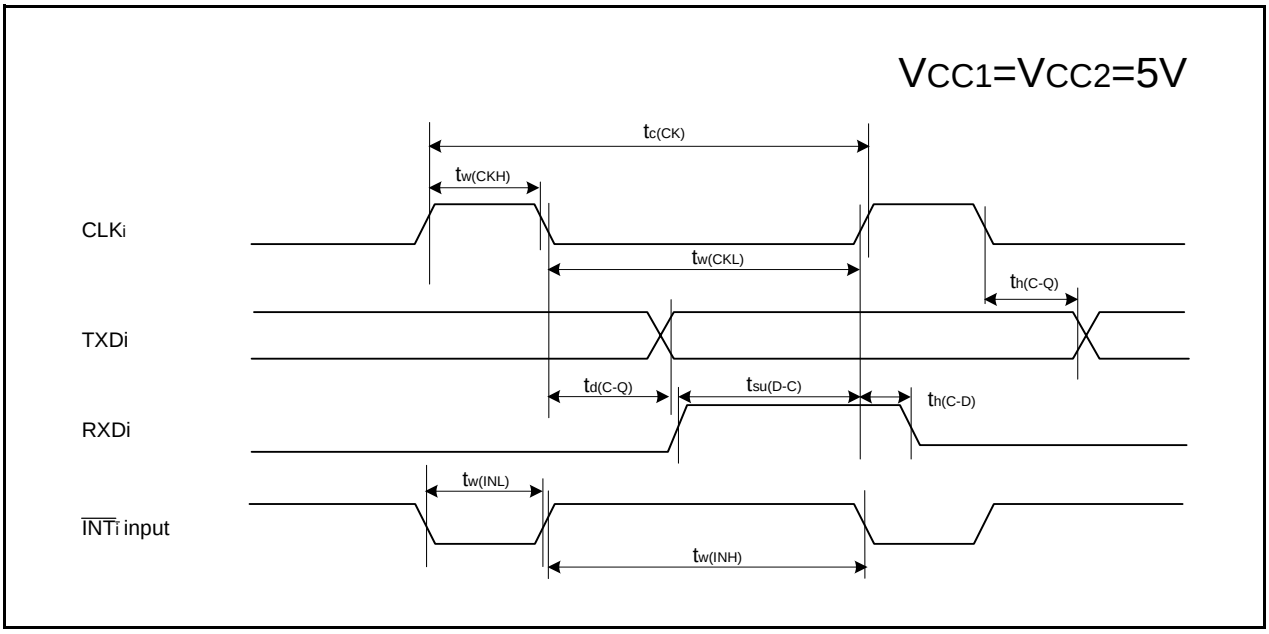


Figure 5.4 Timing Diagram (2)

$V_{CC1}=V_{CC2}=3V$

Timing Requirements

(V_{CC1} = V_{CC2} = 3V, V_{SS} = 0V, at T_{opr} = –20 to 85°C / –40 to 85°C unless otherwise specified)

Table 5.37 Timer B Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time (counted on one edge)	150		ns
$t_{w(TBH)}$	TBiIN Input HIGH Pulse Width (counted on one edge)	60		ns
$t_{w(TBL)}$	TBiIN Input LOW Pulse Width (counted on one edge)	60		ns
$t_{c(TB)}$	TBiIN Input Cycle Time (counted on both edges)	300		ns
$t_{w(TBH)}$	TBiIN Input HIGH Pulse Width (counted on both edges)	120		ns
$t_{w(TBL)}$	TBiIN Input LOW Pulse Width (counted on both edges)	120		ns

Table 5.38 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time	600		ns
$t_{w(TBH)}$	TBiIN Input HIGH Pulse Width	300		ns
$t_{w(TBL)}$	TBiIN Input LOW Pulse Width	300		ns

Table 5.39 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN Input Cycle Time	600		ns
$t_{w(TBH)}$	TBiIN Input HIGH Pulse Width	300		ns
$t_{w(TBL)}$	TBiIN Input LOW Pulse Width	300		ns

Table 5.40 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(AD)}$	$\overline{\text{ADTRG}}$ Input Cycle Time	1500		ns
$t_{w(ADL)}$	$\overline{\text{ADTRG}}$ Input LOW Pulse Width	200		ns

Table 5.41 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi Input Cycle Time	300		ns
$t_{w(CKH)}$	CLKi Input HIGH Pulse Width	150		ns
$t_{w(CKL)}$	CLKi Input LOW Pulse Width	150		ns
$t_{d(C-Q)}$	TXDi Output Delay Time		160	ns
$t_{h(C-Q)}$	TXDi Hold Time	0		ns
$t_{su(D-C)}$	RXDi Input Setup Time	100		ns
$t_{h(C-D)}$	RXDi Input Hold Time	90		ns

Table 5.42 External Interrupt $\overline{\text{INTi}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{\text{INTi}}$ Input HIGH Pulse Width	380		ns
$t_{w(INL)}$	$\overline{\text{INTi}}$ Input LOW Pulse Width	380		ns

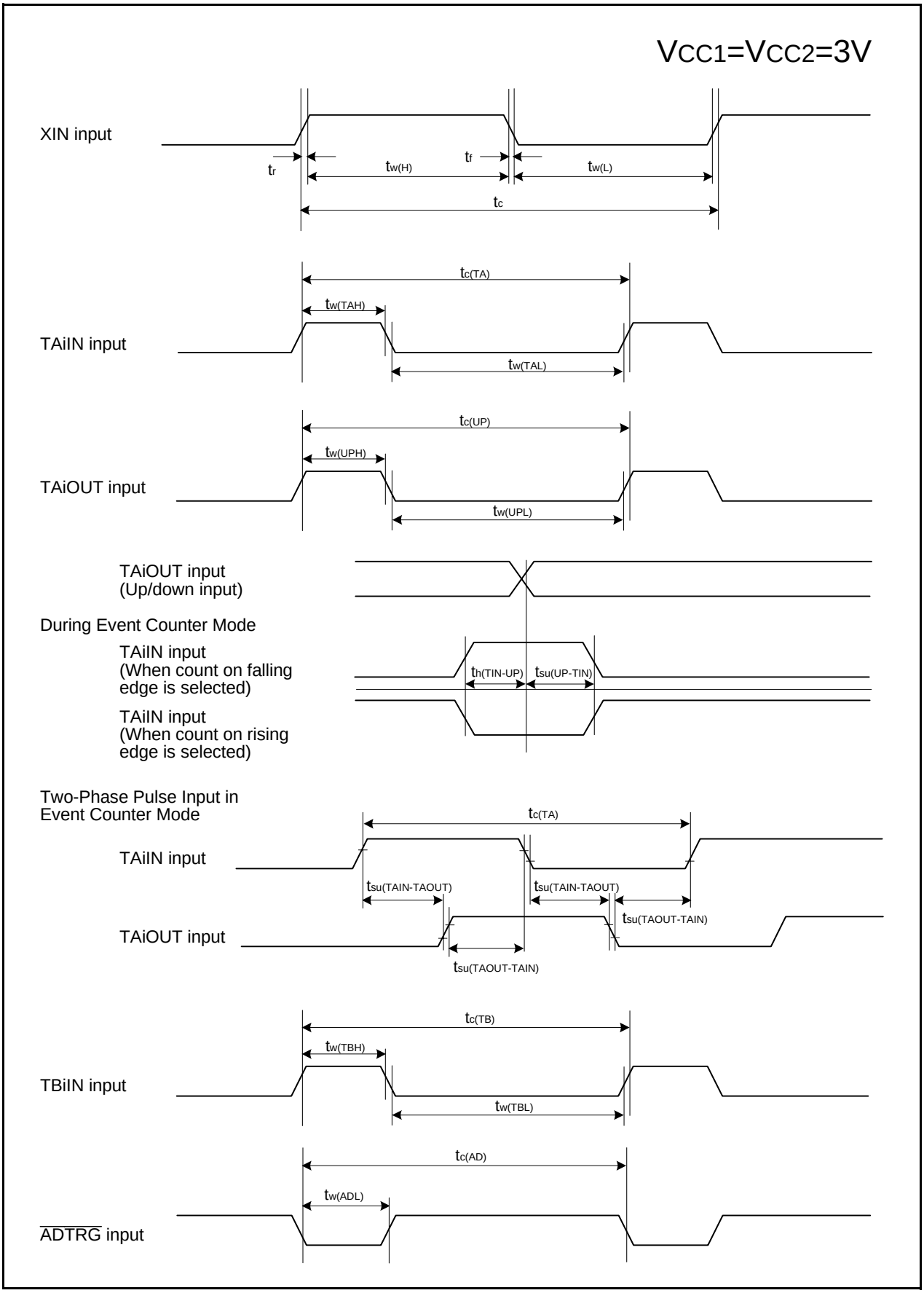
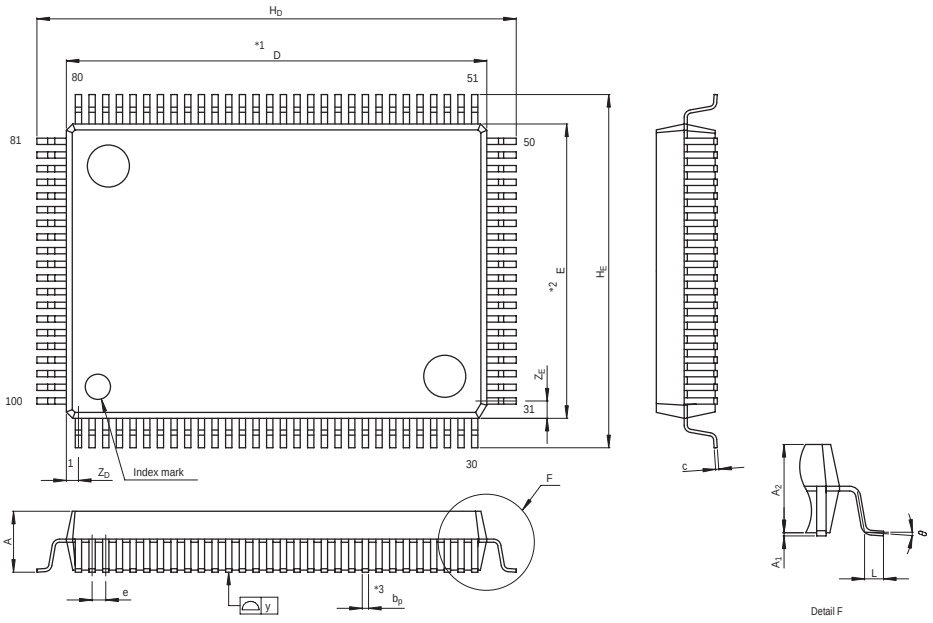


Figure 5.9 Timing Diagram (1)

Appendix 1. Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the "Packages" section of the Renesas Technology website.

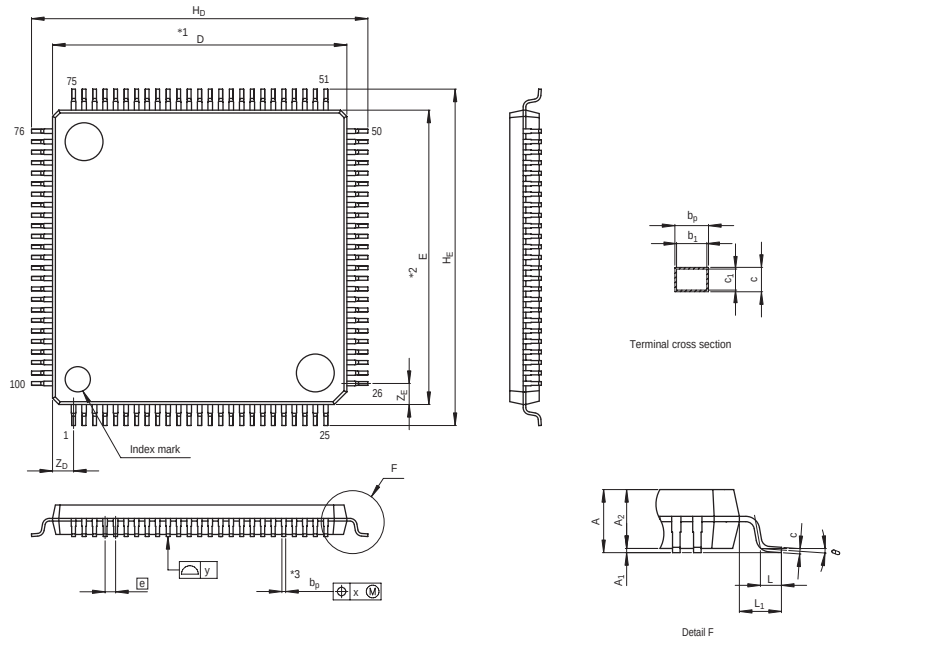
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-QFP100-14x20-0.65	PRQP0100JB-A	100P6S-A	1.6g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	19.8	20.0	20.2
E	13.8	14.0	14.2
A_2	—	2.8	—
H_D	22.5	22.8	23.1
H_E	16.5	16.8	17.1
A	—	—	3.05
A_1	0	0.1	0.2
b_p	0.25	0.3	0.4
c	0.13	0.15	0.2
θ	0°	—	10°
e	0.5	0.65	0.8
y	—	—	0.10
Z_D	—	0.575	—
Z_E	—	0.825	—
L	0.4	0.6	0.8

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Rev.	Date	Description	
		Page	Summary
		44	Figure 5.12 Timing Diagram (4) is added.
		45	Figure 5.13 Timing Diagram (5) is added.
1.10	Oct 01, 2005	2	Table 1.1 Performance Outline of M16C/30P Group is partly revised.
		4	Table 1.2 Product List is partly revised.
			Figure 1.2 Type No., Memory Size, and Package is partly revised.
		5	Table 1.3 Product Code of Mask ROM version Version for M16C/30P is added.
			Figure 1.3 Marking Diagram of Mask ROM Version for M16C/30P is added.
		6	Figure 1.4 Marking Diagram of ROM -less Version for M16C/30P is added.
		6	Table 1.4 Product Code of ROM-less version for M16C/30P is added.
		16	Figure 3.1 Memory Map is partly added.
		23	Table 5.2 information is revised.
1.11	May 31, 2006	4	1.4 Product List information is revised.
			Table 1.2 Product List is partly revised.
		5	Figure 1.2 Type No., Memory Size, and Package is partly added.
		7	Table 1.4 Product Code of Flash Memory version and ROM-less version for M16C/30P is partly revised.
			Figure 1.4 Marking Diagram of Flash Memory version and ROM-less Version for M16C/30P (Top View) is partly added.
		17	3. Memory information is revised.
			Figure 3.1 Memory Map is partly revised.
		18	Table 4.1 SFR Information(1) is partly revised.
		19	Table 4.2 SFR Information(2) is partly added.
		23	Table 5.1 Absolute Maximum Ratings information is revised.
		26	Table 5.4 Flash Memory Version Electrical Characteristics is added.
			Table 5.5 Flash Memory Version Program / Erase Voltage and Read Operation Voltage Characteristics is added.
		28	Table 5.7 Electrical Characteristics(1) is partly deleted.
		29	Table 5.8 Electrical Characteristics (2) is partly revised.
		33	Table 5.23 Memory Expansion and Microprocessor Modes NOTES 3 is partly revised.
		34	Table 5.24 Memory Expansion and Microprocessor Modes NOTES 3 is partly revised.
		40	Table 5.25 Electrical Characteristics (1) is partly deleted.
		41	Table 5.26 Electrical Characteristics (2) is partly revised.
		45	Table 5.41 Memory Expansion and Microprocessor Modes NOTES 3 is partly revised.
		46	Table 5.42 Memory Expansion and Microprocessor Modes NOTES 3 is partly revised.